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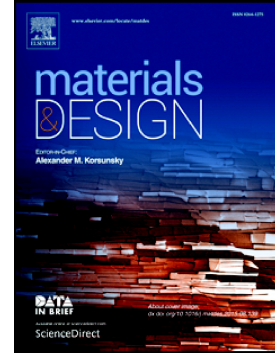
Nanoparticle/solder hybrid joints for next-generation power semiconductor modules

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PII: S0264-1275(17)30310-6
DOI: doi: [10.1016/j.matdes.2017.03.061](https://doi.org/10.1016/j.matdes.2017.03.061)
Reference: JMADE 2895

To appear in: *Materials & Design*

Received date: 17 November 2016
Revised date: 17 March 2017
Accepted date: 20 March 2017



Please cite this article as: Toshikazu Satoh, Toshitaka Ishizaki, Masanori Usui , Nanoparticle/solder hybrid joints for next-generation power semiconductor modules. The address for the corresponding author was captured as affiliation for all authors. Please check if appropriate. Jmade(2017), doi: [10.1016/j.matdes.2017.03.061](https://doi.org/10.1016/j.matdes.2017.03.061)

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